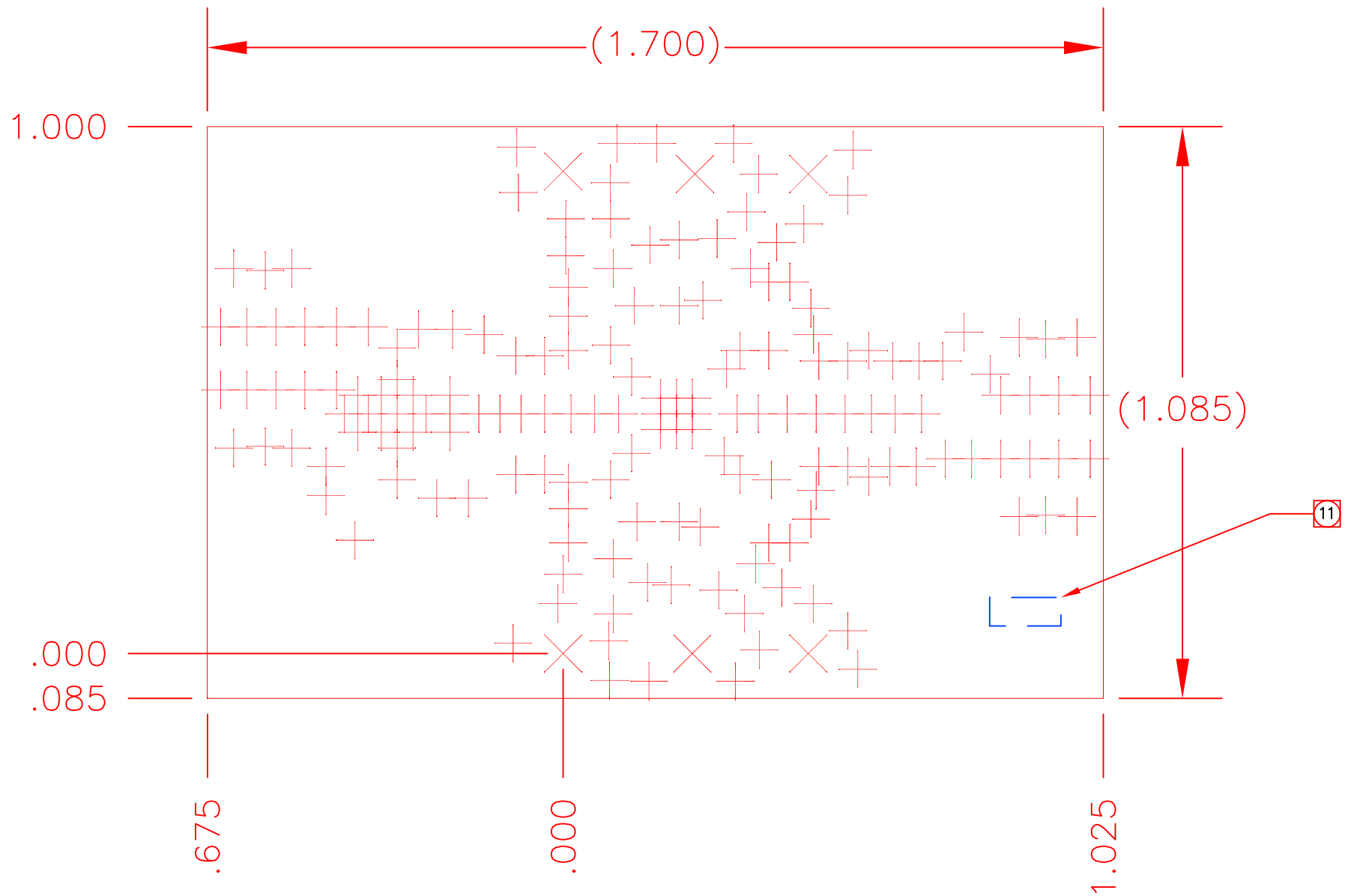
REVISION				
REV	DESCRIPTION	DCN	DATE	BY/APPD

COMPONENT SIDE

NOTES UNLESS OTHERWISE SPECIFIED:

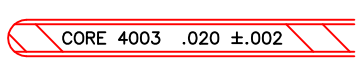
1. FABRICATE IAW IPC–6012, CLASS 2, CURRENT REVISION.
2. BOARD SHALL MEET THE INSPECTION CRITERIA OF IPC–A–600 CLASS 2, CURRENT REVISION.
3. USE ARTWORK 1094098AW CURRENT REV.
4. MATERIAL: 4003. RoHS COMPLIANT. SEE LAYER STACK–UP BELOW.
5. FINISHED WEIGHT OF ALL COPPER LAYERS SHALL BE 1 OZ. PER SQUARE FOOT NOMINAL.
6. DESMEAR HOLES AND VIAS.
7. FINISH: ELECTROLESS NI IMMERSION AU (ENIG). GOLD PLATING THICKNESS TO BE BETWEEN 3 – 8 MICROINCHES.
8. SILKSCREEN TOP SIDE WITH NONCONDUCTIVE EPOXY INK. COLOR SHALL BE A CONTRASTING INK WITH RESPECT TO SOLDERMASK COLOR. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. REMOVE EPOXY INK FROM SOLDER LANDS.
9. APPLY SOLDERMASK OVER BARE COPPER (SMOBC) IAW IPC–SM–840, TOP SIDE, USING LPI, COLOR CLEAR OR GREEN. SOLDERMASK OVER VIAS IS NOT ACCEPTABLE.
10. TANGENCY IS ACCEPTABLE.
11. SUPPLIER LOT NUMBER/DATE CODE (NO LOGO) SHALL ONLY BE SILKSCREENED WITH NON–CONDUCTIVE EPOXY INK IN APPROX. LOCATION SHOWN.



2 LAYER
CROSS SECTION
FILM SET
5

LAYER 1 – COMP SIDE
LAYER 2 – BOTTOM SIDE

2 LAYER
CROSS SECTION
DIMENSIONAL TOLERANCE



HOLE SCHEDULE (ALL PLATED THRU DIAMETERS ARE AFTER PLATING)			
SYM	DESCRIPTION	PLATED THRU	QTY
+	ø.010 +.006/–.000 THRU	YES	168
×	ø.060 ±.003 THRU	YES	6

QTY PER DASH NO	ITEM NO	PART OR IDENT NO	CAGE CODE	NOMENCLATURE OR DESCRIPTION	SPEC/STD
PARTS LIST OR MATERIAL					

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES, TOLERANCES ON XX DEC ± .02, XXX DEC ± .005, FINISH 63 RMS, ANGLES ± 0° 30'

TriQuint SEMICONDUCTOR SAN JOSE, CALIFORNIA

MATERIAL: 4

FINAL PROTECTIVE FINISH: 7

DR	K. KELSEN	5–7–12
CHK		
ENG	C. BLUM	5–7–12
MFG		
QA		
TF		
CONT NO.		

PRINTED CIRCUIT BOARD
TQP3M9039

SIZE	CAGE CODE		REV
D	14482	1094098PC	–

SCALE NONE W/O NO. SHEET 1 OF 1

1094098PC

TriQuint SEMICONDUCTOR PROPRIETARY INFORMATION

DSIZE 7/8/08